

PCN Number:	20181022003.0	PCN Date:	October 24, 2018
Title:	Datasheet for TMP302, TMP102		
Customer Contact:	PCN Manager	Dept:	Quality Services
Change Type:			
<input type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Design
<input type="checkbox"/>	Assembly Process	<input checked="" type="checkbox"/>	Data Sheet
<input type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change
<input type="checkbox"/>	Mechanical Specification	<input type="checkbox"/>	Test Site
<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Site
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Material
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Process
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Site
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Materials
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Process

Notification Details

Description of Change:

Texas Instruments Incorporated is announcing an information only notification. The product datasheet(s) is being updated as summarized below. The following change history provides further details.



TMP302

SBOS488D – JUNE 2009 – REVISED OCTOBER 2018

Changes from Revision C (August 2015) to Revision D	Page
• Changed the supply voltage maximum value from: 3.6 V to: 4 V	4
• Changed the input pin supply voltage maximum value from: $V_S + 0.5$ V to: $V_S + 0.5$ and ≤ 4 V	4
• Changed the output pin voltage maximum value from: 3.6 V to: 4 V	4
• Updated junction-to-ambient thermal resistance from 200 to 210.3	4
• Updated junction-to-case (top) thermal resistance from 73.7 to 105.0	4
• Updated junction-to-board thermal resistance from 34.4 to 87.5	4
• Updated junction-to-top characterization parameter from 3.1 to 6.1	4
• Updated junction-to-board characterization parameter from 34.2 to 87.0	4
• Added <i>Receiving Notification of Documentation Updates</i> section	12



TMP102

SBOS397G – AUGUST 2007 – REVISED OCTOBER 2018

Changes from Revision F (December 2015) to Revision G	Page
• Changed input voltage maximum value from: 3.6 V to: 4 V	4
• Changed output voltage maximum value from: 3.6 V to: $(V^+) + 0.5$ and ≤ 4 V	4
• Changed Junction-to-ambient thermal resistance from 200 °C/W to 210.3 °C/W	5
• Changed Junction-to-case (top) thermal resistance from 73.7 °C/W to 105.0 °C/W	5
• Changed Junction-to-board thermal resistance from 34.4 °C/W to 87.5 °C/W	5
• Changed Junction-to-top characterization parameter from 3.1 °C/W to 6.1 °C/W	5
• Changed Junction-to-board characterization parameter from 34.2 °C/W to 87.0 °C/W	5
• Added the <i>Receiving Notification of Documentation Updates</i> section	24

The datasheet number will be changing.

Device Family	Change From:	Change To:
TMP302	SBOS488C	SBOS488D
TMP102	SBOS397F	SBOS397G

These changes may be reviewed at the datasheet links provided.

<http://www.ti.com/product/TMP302>

Reason for Change:

To accurately reflect device characteristics.

Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

No anticipated impact. This is a specification change announcement only. There are no changes to the actual device.

Changes to product identification resulting from this PCN:			
None.			
Product Affected:			
TMP302ADRLR	TMP302ADRLT	TMP302BDRLR	TMP302DDRLT
TMP302CDRLR	TMP302CDRLT	TMP302DDRLR	TMP102AIDRLRG4
HPA00330AIDRLR	HPA00330AIDRLRG4	TMP102AIDRLR	
TMP102AIDRLT	TMP102AIDRLTG4	TMP302BDRLT	

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com